

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1-14. (canceled).

15. (previously presented) A method for producing a metal/ceramic bonding article, said method comprising the steps of:

arranging a metal member of an alloy containing copper and nickel on at least one side of a ceramic substrate;

arranging said metal member, which is arranged on said at least one side of said ceramic substrate, on a supporting plate via a spacer;

arranging a weight thereon via a spacer; and

heating said metal member and said ceramic substrate in vacuo at a temperature between solidus and liquidus lines of said alloy to bond said metal member directly to said ceramic substrate,

wherein said heating step is carried out in a vacuum furnace.

16-19. (canceled).

20. (previously presented) A method for producing a metal/ceramic bonding article as set forth in claim 15, wherein said alloy is an entire-rate solid solution type alloy.

21. (previously presented) A method for producing a

metal/ceramic bonding article as set forth in claim 15, wherein said alloy contains manganese.

22. (previously presented) A method for producing a metal/ceramic bonding article as set forth in claim 21, wherein said alloy contains 1.0 to 4.0 wt% of nickel, 10.0 to 13.0 wt% of manganese and the balance being copper and unavoidable elements.

23. (previously presented) A method for producing a metal/ceramic bonding article as set forth in claim 15, wherein said temperature between solidus and liquidus lines of said alloy is not higher than a temperature which is higher than said solidus line of said alloy by 50°C.

24. (previously presented) A method for producing a metal/ceramic bonding article as set forth in claim 15, wherein said alloy is a manganin alloy, and said temperature between solidus and liquidus lines of said alloy is in the range of from 960°C to 990°C.

25. (previously presented) A method for producing a metal/ceramic bonding article as set forth in claim 15, wherein a thinner plate than said metal member is provided on a peripheral portion of said metal member.

26. (previously presented) A method for producing a metal/ceramic bonding article as set forth in claim 25, wherein said plate has a thickness of 0.2 mm or less.

27. (previously presented) A method for producing a metal/ceramic bonding article as set forth in claim 15, wherein

plating is carried out on the whole or part of a surface of said metal member.

28. (previously presented) A method for producing a metal/ceramic bonding article as set forth in claim 15, wherein said metal/ceramic bonding article is an electronic member for resistance.